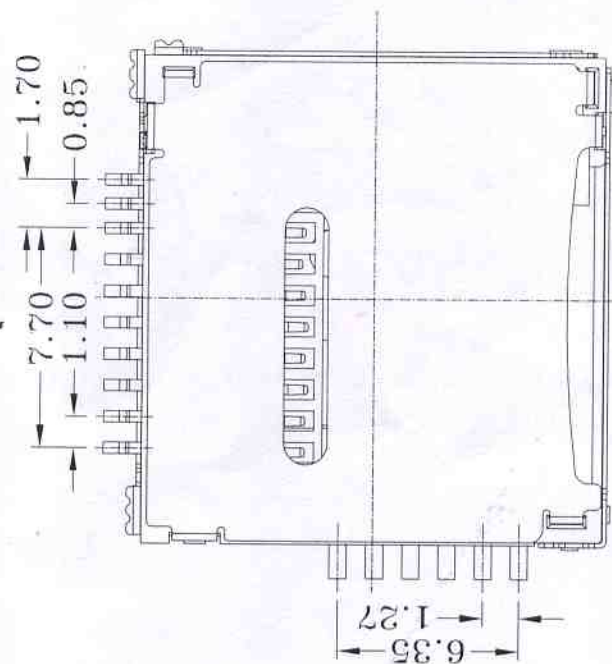
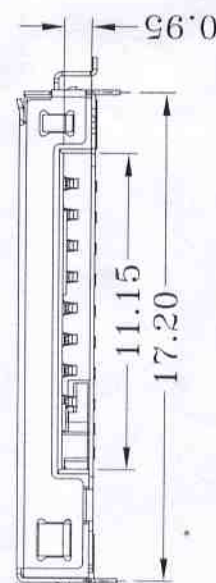
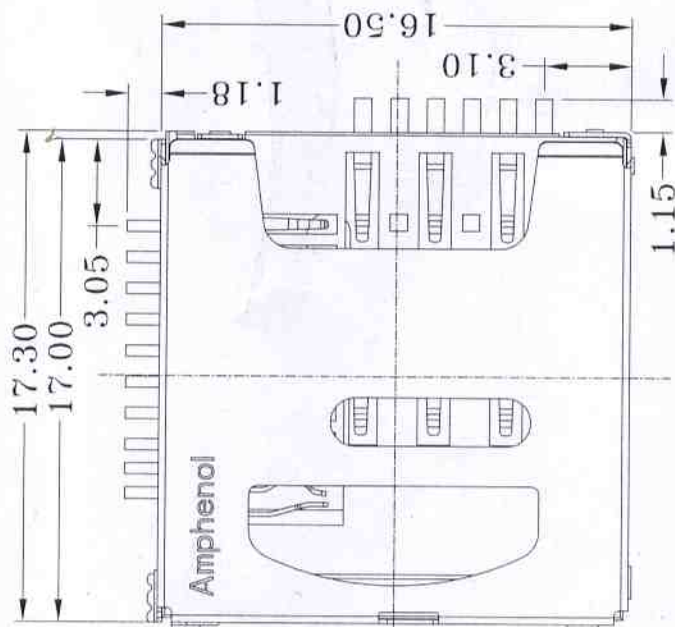


REV.	ECN NO.	MODIFY CONTENT	DATE
A	ES D0712.115	Initial Release	2007/12/25
B	ES D0904.064	Add plating code	2008/1/14
C	ES D0807.128	Modify shell solder tail	2008/07/24



101-00434-**-**

- 64:Plating Au1u" on contact area, 160u" Min. Bright Tin on solder tail.
65:Plating Au3u" on contact area, 160u" Min. Bright Tin on solder tail.
66:Plating Au5u" on contact area, 160u" Min. Bright Tin on solder tail.
67:Plating Au10u" on contact area, 160u" Min. Bright Tin on solder tail.
68:Plating Au10u" on contact area, 160u" Min. Bright Tin on solder tail.
69:Plating Au30u" on contact area, 160u" Min. Bright Tin on solder tail.

GENERAL TOLERANCE		FILE NO.		10100434		PART NO.		DRAWN		Paul		MATERIAL		SCALE		1:1			
.X $\pm$ 0.50		x. * $\pm$ 5 *		REV.		C		SIM+Micro-SD P/P CARD CONN.		CHECKED		DATE		2008/07/24		UNITS		MM	
.X $\pm$ 0.38		.x * $\pm$ 2 *		SIZE				TITLE											
.XX $\pm$ 0.25		.xx $\pm$ 1 *		A4				SHEET		1 OF 3									

1

2

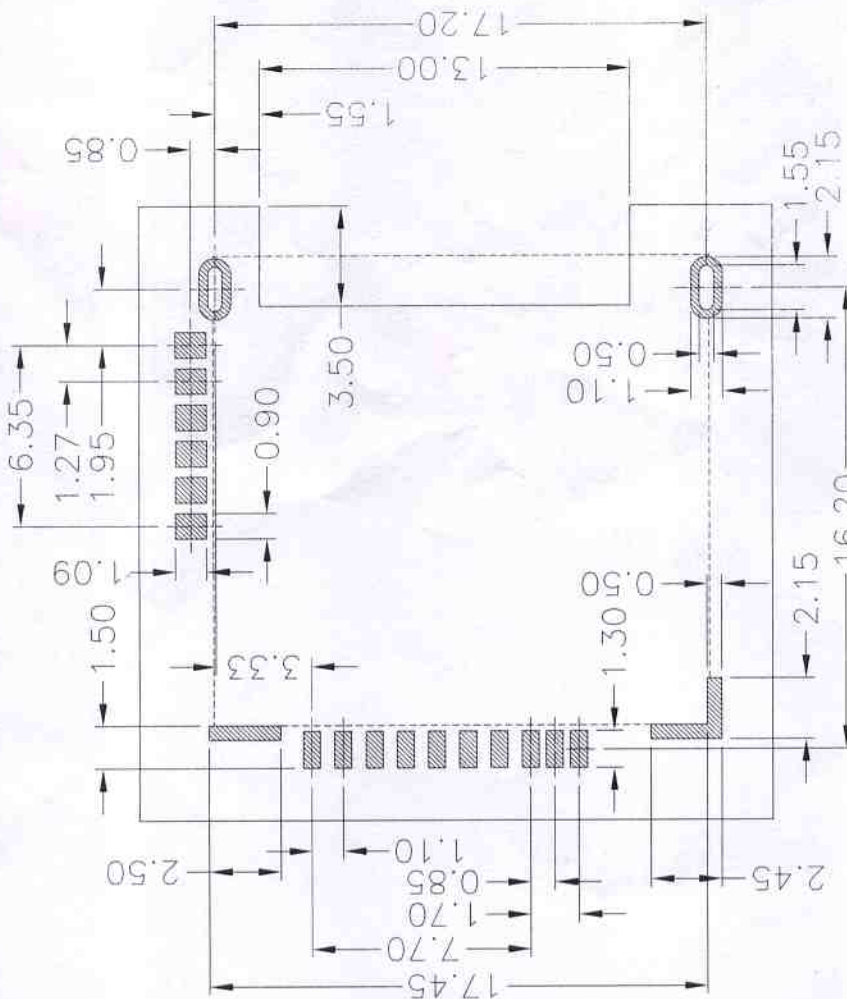
3

4

5

Amphenol Shouhmin Industry

REV.	ECN NO.	MODIFY CONTENT	DATE
A	ES.D0712.115	Initial Release	2007/12/25
B	ES.D0804.64	Add plating code	2008/1/14
C	ES.D0807.128	Modify shell solder tail	2008/07/24



PCB LAYOUT

GENERAL		TOLERANCE	FILE NO.		. 10100434		PART. NO.		10100434**		DRAWN		Paul		MATERIAL		SCALE		1:1			
X $\pm$ 0.50		X $\pm$ 5 $^{\circ}$	REV.		C		TITLE		SIM+Micro-SD P/P CARD CONN.		CHECKED				DATE		2008/07/24		UNITS		MM	
X $\pm$ 0.38		X $\pm$ 2 $^{\circ}$	SIZE				SHEET		2 OF 3		APPROVED											
XX $\pm$ 0.25		XX $\pm$ 1 $^{\circ}$	A4																			
Amphenol Shouhmin Industry																						

